

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10826713			
<b>Filing Date:</b>	16-Apr-2004			
<b>Title of Invention:</b>	Wafer-level assembly method for chip-size devices having flipped chips			
First Named Inventor/Applicant Name:	William D. Boyd			
<b>Filer:</b>	Yingsheng Tung/Jackie McBride			
<b>Attorney Docket Number:</b>	TI-37214			
Filed as Large Entity				
<b>Utility</b>	<b>Filing Fees</b>			
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
Post-Allowance-and-Post-Issuance:				
<b>Extension-of-Time:</b>				
Extension - 2 months with \$0 paid	1252	1	450	450

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				450